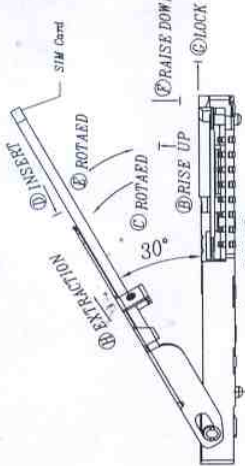
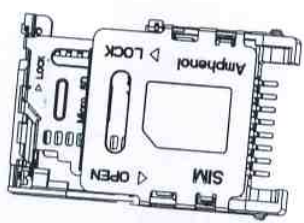


| REV | ECN NO. | MODIFY CONTENT | DATE |
|-----|--------------|-----------------|------------|
| E | ES 10006.071 | add post length | 2009/06/04 |

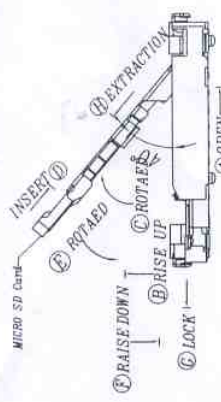


SIM OPERATION STEP

HOW TO INSERT AND EXTRACT

INSERT PROCESS: ① → ② → ③ → ④ → ⑤ → ⑥ → ⑦ → ⑧

EXTRACT PROCESS: ⑧ → ⑦ → ⑥ → ⑤ → ④ → ③ → ② → ①

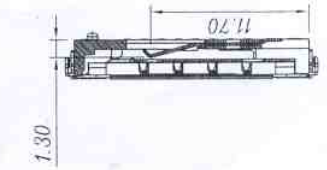
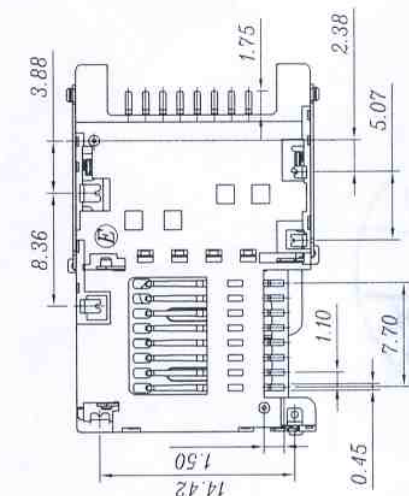
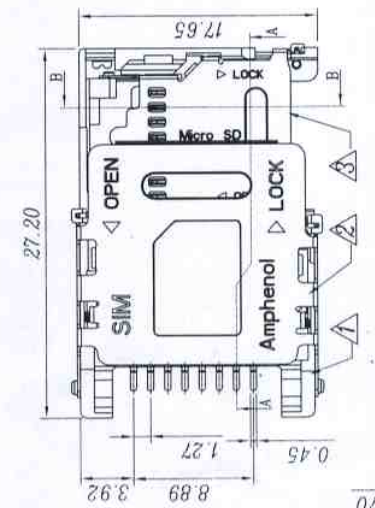
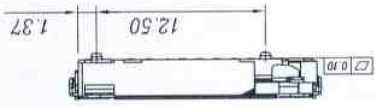
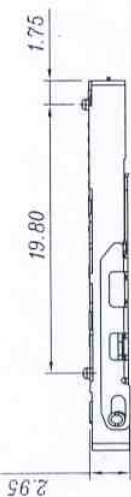


MICRO SD OPERATION STEP

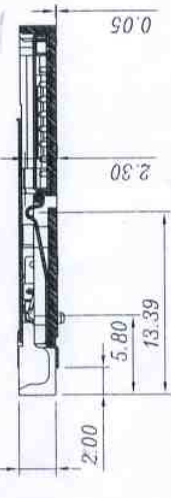
HOW TO INSERT AND EXTRACT

INSERT PROCESS: ① → ② → ③ → ④ → ⑤ → ⑥ → ⑦ → ⑧

EXTRACT PROCESS: ⑧ → ⑦ → ⑥ → ⑤ → ④ → ③ → ② → ①

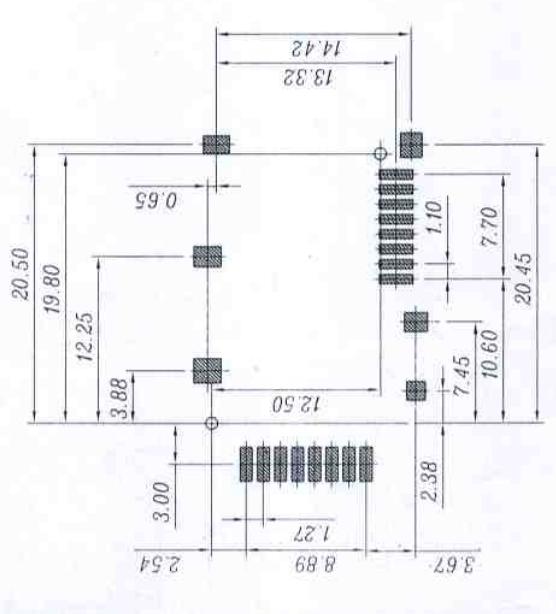
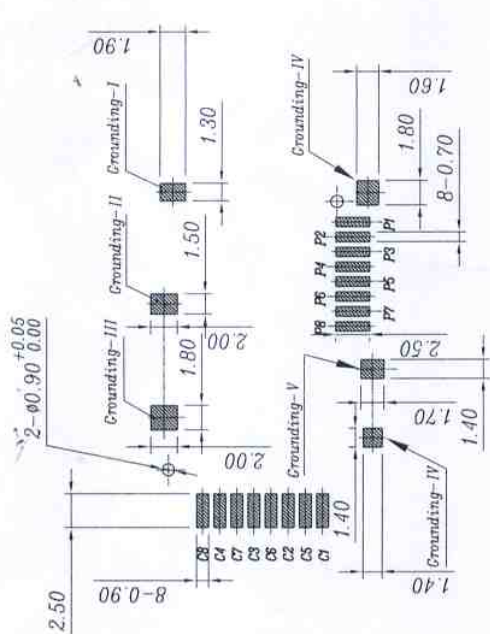
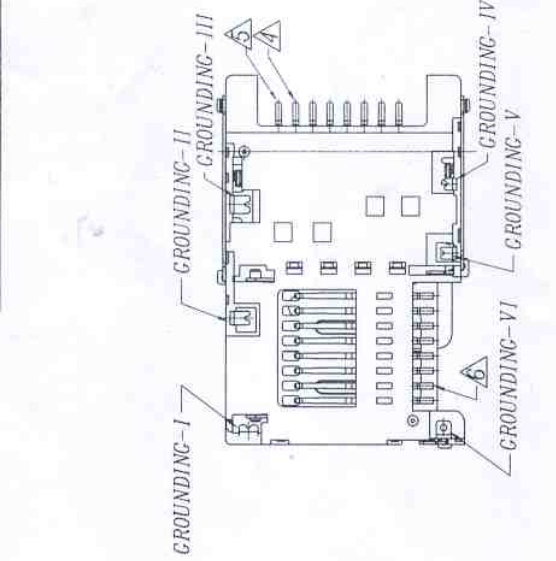


SECTION B-B
SCALE 1:1



SECTION A-A
SCALE 1:1

| GENERAL | TOLERANCE | FILE NO. | 10100492 | PART NO. | 10100492** | DRAWN | lily li | MATERIAL | SCALE | 2:1 | |
|------------|-----------|----------|----------|----------|--------------------|----------|---------|----------------------------|--------------------------------------|------|----|
| X ± 0.50 | x. * ± 5' | REV. | E | TITLE | SIM+MICRO SD CONN. | CHECKED | Jane | DATE | 2009/06/04 <td>UNIT</td> <td>mm</td> | UNIT | mm |
| .X ± 0.38 | .x * ± 2' | SIZE | | SHEET | 1/2 | APPROVED | Henry | Amphenol Shouhmin Industry | | | |
| .XX ± 0.25 | .xx ± 1' | A4 | | | | | | | | | |



RECOMMENDER P.C.B LAYOUT
 (ALL TOLERANCES:0.03mm)

NOTE:
 1.MATERIAL
 A.INSULATOR: HIGH TEMPERATURE THERMOPLASTIC,UL194 V-0.
 B.SHELL:STAINLESS STEEL.
 C.CONTACT: COPPER ALLOY.
 2.PLATED:
 CONTACT AREA: GOLD 1~50µ" SELECTIVE
 SOLDER TAIL:TIN PLATED OR GOLD FLASH
 UNDERPLATING :50µ" NICKEL
 3.PAD:GOLD PLATING OVER NICKEL.

PART. NO.
 10100492**

- 04: Contact area 3µ", other area gold flash.
- 05: Contact area 5µ", other area gold flash.
- 06: Contact area 10µ", other area gold flash.
- 07: Contact area 15µ", other area gold flash.
- 08: Contact area 30µ", other area gold flash.
- 17: Contact area 1µ". Solder tail plating gold flash.
- 18: Contact area 3µ". Solder tail plating gold flash.
- 19: Contact area 5µ". Solder tail plating gold flash.
- 20: Contact area 15µ". Solder tail plating gold flash.
- 21: Contact area 30µ". Solder tail plating gold flash.
- 22: Contact area 50µ". Solder tail plating gold flash.

| SIM pin assignment | | Micro SD pin assignment | |
|--------------------|----------|-------------------------|-----------------|
| PIN# | Name | PIN# | Name |
| C1 | VCC | P1 | DAT2 |
| C2 | RST | P2 | CD/DAT3* |
| C3 | CLK | P3 | CMD |
| C4 | Reserved | P4 | Y ₀₀ |
| C5 | GND | P5 | CLK |
| C6 | VPP | P6 | VSS |
| C7 | I/O | P7 | DAT0 |
| C8 | Reserved | P8 | DAT1 |

MATERIALS & PLATINGS TABLE

| ITEM | DESCRIPTION | Q'TY | MATERIAL |
|------|--------------------|------|-------------------------|
| △ | TERMINAL/GROUNDING | 8 | PHOSPHER BRONZE(t=0.20) |
| △ | SIM TERMINAL-II | 4 | PHOSPHER BRONZE(t=0.20) |
| △ | SIM TERMINAL-I | 4 | PHOSPHER BRONZE(t=0.20) |
| △ | MICRO SD SHELL | 1 | STAINLESS STEEL(t=0.20) |
| △ | SIM SHELL | 1 | STAINLESS STEEL(t=0.20) |
| △ | INSULATOR | 1 | LCP UL 94V-0 |

| GENERAL | TOLERANCE | FILE. NO. | 10100492 | PART. NO. | 10100492** | DRAWN | lily li |
|------------|-----------|-----------|----------|-----------|--------------------|----------|---------|
| X ± 0.50 | x ± 5' | REV. | E | TITLE | SIM+MICRO SD CONN. | CHECKED | June |
| .X ± 0.38 | .x ± 2' | SIZE | | SHEET | 2/2 | APPROVED | Henry |
| .XX ± 0.25 | .xx ± 1' | A4 | | | | | |

Amphenol Shouhmin Industry